

Preparation and Characterization of Ni-coated Aluminum Powder by Electroless Plating

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ABSTRACT: This paper deals with the preparation and characterization of Nickel-coated Aluminum ceramic particles by Electroless Plating Technique. Aluminum powder is used for plating. The bath for Electroless Nickel Plating is prepared with some chemicals like Nickel Chloride hexahydrate, Sodium hypophosphate Monohydrate, Ammonium Chloride, Tri Sodium Citrate, Sodium Hydroxide. A bath temperature of 85°C, pH value of 8 and stirring time of 20 min is considered to carry out the deposition. And we checked for the colour change, hardness and density values have given the primary indications and the results of SEM (scanning electron microscopy) is whether convincing or not. The results shown a great change in colour change i.e, deposition of nickel is rich that indicates the coating is done on the Aluminum powder, also there is a great change in density.

1. INTRODUCTION

Aluminum ceramics are widely used as reinforcement in many applications of modern metal matrix composite materials. However, engineering applications of a ceramic material are determined by its brittleness. The composite preparation also suffers from low wettability because of liquid metal and ceramic interactions. As the bonding between metal and ceramic plays a prominent role in deciding the characteristic of the composite, the research is focused at the methods of improving wettability. One such method is modifying the particulate-reinforcement surface using a metal coating as layer. Nickel, known for its excellent corrosion and wear resistance, is a good choice for a coating material. A few methods like co-precipitation method, sol-gel method are employed to prepare the coated powder. On the other hand, the electroless plating method is another option with an advantage in high deposition rate, simple operation and capability of mass production. Another advantage of using electroless nickel is its ability to produce the deposits with a very high degree of uniformity of thickness. The Ni deposit has a good wettability and is generally hard. The Electroless plating proposed by Brenner and Riddell has been widely used during the past two decades in many applications.

2. RAW MATERIALS

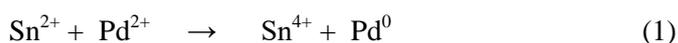
99% pure Aluminium powders of average particle size 50 nm, supplied by Aahila Plastic Processing Industry, Hyderabad are used in the present experiment. The primary characteristics of the powder are shown in Table 1. The chemicals which are required for Pre-treatment Process and Composition and Conditions of the Bath are supplied from Growwell Scientific and surgicals, Laboratory equipment supplier in Rajahmundry, India. These are clearly shown in Table 2 and 3.

Particle Size	50 nm (Avg. Size)
Purity	99 %
Density	3.9 g/cm ³
Crystal Structure	FCC
Appearance	Light Grey Solid

Table:1 Characteristics of the Al₂O₃ Powders used in the Experiment

3. MECHANISM OF PLATING

The basic principle of Electroless plating is similar to Electro Plating but without many Electrical Contacts and apparatus. Charge transfer takes place through a chemical reduction process. The Electroless plating depends upon the catalytic reduction of a metallic ion in an aqueous solution containing a reducing agent and the subsequent deposition of the metal without the use of electrical energy. In this experiment, Nickel Chloride Hexahydrate (NiCl₂.6H₂O) is used as a source of Nickel ions while Sodium hypophosphite (NaH₂PO₂.H₂O) is the reducing agent. The pre-treatment of the powder (Sensitization and Activation) makes the conditions favorable for plating. The nickel deposition with SnCl₂ sensitization and PdCl₂ activation is employed in the present work. In the sensitization process, Sn²⁺ ions are absorbed on the surface of the Aluminium powders, which could facilitate attracting of Pd²⁺ ions onto the surface of particles (Eq. 1). When the activated Aluminium powders are added to the bath, the metallic nickel could be deposited with the following reactions (Eq. 2 & Eq. 3) taking place.



The Ni²⁺ ions will be reduced to metallic nickel and the metallic Pd⁰ oxidized to Pd²⁺. That is, both oxidation and reduction reactions happen in the process.

4. EXPERIMENTAL PROCEDURE

The plating process involves two steps, Viz. Pretreatment (Surface preparation) and Bathing. Initially, the powder was treated with acetone using Ultrasonic cleaner and later on with different chemicals to complete the pretreatment process. Xu *et al.*, reported Ultrasonic agitation promotes better nucleation and deposition of nickel than mechanical agitation in case of nickel-coated graphite [10]. The detailed description of the chemicals and their purposes used for experimentation are mentioned in the Table 2. The powders are rinsed with distilled water and are dried in each step.

The pretreated powder is sent to the electroless nickel deposition bath. The alkaline solution bath was adapted for the advantage of having low phosphorous content [7]. The bath elements used here are less in quantity and have an economical advantage than those proposed by pang *et al.*, [4]. The deposition bath for plating was prepared using the formulations given in the literature [8] and is indicated in Table 3

In this experiment, in addition to adopting the SnCl₂ sensitization and PdCl₂ activation process in Ref. [7], rinsing of the sensitized Aluminium powders was intentionally applied for the Ni electroless deposition. Firstly, the Aluminium powders were immersed in acetone solution with ultrasonic agitation for 20 min to clean the surface. Secondly, the powders were sensitized in an aqueous solution of 5 g/L SnCl₂.6H₂O and 15 ml/L HCl for 10 min. Finally, the Aluminium powders were activated in an aqueous solution of 0.125 g/L PdCl₂ and 1.5 ml/L HCl for 10 min. The powders were rinsed with distilled water in each step and

dried in oven after the pretreatment processes. In order to investigate the effect of Sn^{2p} absorption behaviors on electroless nickel plating, different SnCl₂ sensitization conditions were controlled to prepare powders. In the electroless deposition process, a NaOH solution (30 wt%) was used to adjust the pH to a value of about 8. The powders were electroless deposited for 20 min at a temperature of 85⁰C, followed by thoroughly rinsing and drying for characterization.

Chemicals and Conditions	Concentration
Nickel chloride, hexahydrate (NiCl ₂ .6H ₂ O)	15 g/L
Sodium hypophosphite Mono Hydrate (NaH ₂ PO ₂ .H ₂ O)	12.5 g/L
Ammonium Chloride (NH ₄ Cl)	25 g/L
Tri Sodium Citrate (Na ₃ C ₆ H ₅ O ₇ . 2H ₂ O)	20 g/L
Sodium Hydroxide (NaOH)	To maintain the required pH
Bath Temperature	85±2 ⁰ C
pH	8
Time	20 Min

Table:2 Pretreatment Process

Process	Chemicals	Concentration	Time	Purpose
Ultra Sonic Cleaning	Acetone		20 Min	Removes Volatile compounds from the surface and makes the particle surface clean
Etching	HNO ₃	5ml/L	15 Min	Microscopic Roughening
Rinsing	Distilled Water		5 Min	
Sensitization	SnCl ₂ . 6H ₂ O + HCl	5 g/L 15 ml/L	15 Min	Breaks the surface integrity and makes ready for activation
Rinsing	Distilled Water		5 Min	
Activation	PdCl ₂ + HCl	0.125g/L 1.5ml/L	15 Min	Activate the pores and prepare the surface for plating
Rinsing	Distilled Water		5 Min	

Table:3 Composition and Conditions of the Bath



Fig:1 Aluminium powder mixed with 5ml Nitric acid and half litre distilled water



Fig:2 Vacuum filter which is to be used for the filtering of powder from water



Fig:3 Heating upto 85°C in water bath and checking temperature by thermometer



Fig:4 Ni-coated Aluminium powder

5. CHARACTERIZATION OF POWDERS

The surface morphology of the Aluminium powders before and after electroless Ni deposition was characterized by scanning electron microscope (SEM, JSM-6460LV) equipped with an energy dispersive spectroscopy (EDS) at Andhra Univeristy ,Visakhapatnam,India.

6. RESULTS AND DISCUSSIONS

From the literature, the reduction of nickel is always accompanied by the evolution of hydrogen gas [7]. The reaction of hypophosphite (Eq. 2) is the main reason. When the Samples B and C were added to the bath for plating at the conditions specified, the hydrogen gas was evolved in Samples C (Figure 15b) and liberation was very poor in the Sample B (Figure 15a). The color change may justify the presence of Nickel in Samples C.



(a) Sample B

(b) Sample C

Figure 5. Evolution of Hydrogen Gas during Plating Process

The photographs of Sample A, B and C after plating were shown in following figures. The color of the powders was darker in sequence. The color of Sample A is light grey, while the color of Sample B is thick grey and Sample C is black. . The darker the color the rich in deposition of Ni[7]. These results indicated the possible signs of good Ni deposition in Sample C. The reason for less color change in Sample B may be due to the absorbed Sn^{+2} ions on the surface of Aluminium particles during sensitization process being rinsed out because of washing more times [7]. So it does not acquire enough strength to attract nickel from the bath. Clearly shown in figures



a) Sample A

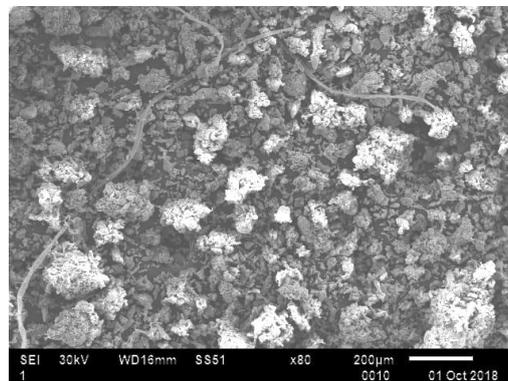
b) Sample B



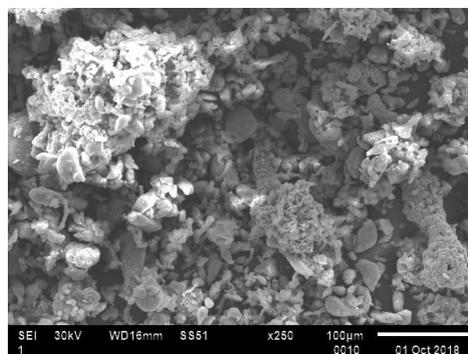
c) Sample C

Figure 6. Optical Photographs of Raw and Electroless Ni Deposited Powders under Different Conditions

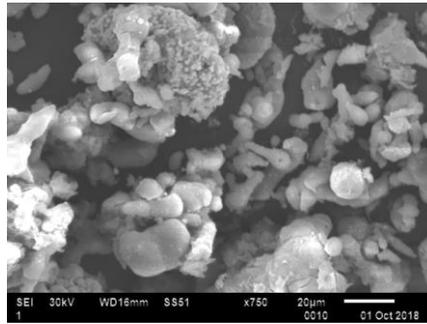
Figure 7 shows the SEM photographs of Aluminium powders before and after electroless deposition. It can be seen that the surface of raw powders were smooth and featureless [Fig. 7(a)]. After electroless nickel deposition, uniform and nanosized nickel particles instead of continuous Ni layers were observed adhering onto the surface of Aluminium particles for sample B [Fig. 7(b)]. Furthermore, it can be seen that the surface of powders of sample C were completely covered with large amount of nickel particles [Fig. 7(c)].



a) Sample A



b) Sample B



c) Sample C

Figure 7. SEM images of the eletroless Ni deposited powders.

7. CONCLUSIONS

The present work shows a possibility to deposit different forms of Ni on surface of Aluminum particles. It is found that the SnCl_2 sensitization process and the subsequent PdCl_2 activation process monitored the formation of Ni layer on aluminium particles. The Sn^{2+} ions are weakly adsorbed on the surface of aluminium particles, and can be rinsed out by distilled water after sensitization process. The rinsing will lead to less/ no Pd on particle surface, while the structure of Ni layer is determined by the distribution structure of Pd around the Aluminium particles during the activation process. The size of nickel particles adhering to the surface of the Aluminium particles were about 50–80 nm.

8. REFERENCES

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